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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

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Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc74at-04i-pt

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

## **Table of Contents**

1.0 General Description	5						
2.0 PIC16C7X Device Varieties	7						
3.0 Architectural Overview	9						
4.0 Memory Organization	19						
5.0 I/O Ports	43						
6.0 Overview of Timer Modules	57						
7.0 Timer0 Module	59						
8.0 Timer1 Module	65						
9.0 Timer2 Module	69						
10.0 Capture/Compare/PWM Module(s)							
11.0 Synchronous Serial Port (SSP) Module							
12.0 Universal Synchronous Asynchronous Receiver Transmitter (USART)	99						
13.0 Analog-to-Digital Converter (A/D) Module	. 117						
14.0 Special Features of the CPU							
15.0 Instruction Set Summary	. 147						
16.0 Development Support							
17.0 Electrical Characteristics for PIC16C72							
18.0 Electrical Characteristics for PIC16C73/74							
19.0 Electrical Characteristics for PIC16C73A/74A							
20.0 Electrical Characteristics for PIC16C76/77	. 219						
21.0 DC and AC Characteristics Graphs and Tables							
22.0 Packaging Information	. 251						
Appendix A:							
Appendix B: Compatibility	. 263						
Appendix C: What's New	. 264						
Appendix D: What's Changed							
Appendix E: PIC16/17 Microcontrollers	. 265						
Pin Compatibility							
Index	. 273						
List of Examples	. 279						
ist of Figures							
ist of Tables							
Reader Response							
PIC16C7X Product Identification System							

For register and module descriptions in this data sheet, device legends show which devices apply to those sections. As an example, the legend below would mean that the following section applies only to the PIC16C72, PIC16C73A and PIC16C74A devices.

## Applicable Devices 72 73 73A 74 74A 76 77

12|13|13A|14|14A|16|11

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## 3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC16CXX family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC16CXX uses a Harvard architecture, in which, program and data are accessed from separate memories using separate buses. This improves bandwidth over traditional von Neumann architecture in which program and data are fetched from the same memory using the same bus. Separating program and data buses further allows instructions to be sized differently than the 8-bit wide data word. Instruction opcodes are 14-bits wide making it possible to have all single word instructions. A 14-bit wide program memory access bus fetches a 14-bit instruction in a single cycle. A twostage pipeline overlaps fetch and execution of instructions (Example 3-1). Consequently, all instructions (35) execute in a single cycle (200 ns @ 20 MHz) except for program branches.

The table below lists program memory (EPROM) and data memory (RAM) for each PIC16C7X device.

Device	Program Memory	Data Memory
PIC16C72	2K x 14	128 x 8
PIC16C73	4K x 14	192 x 8
PIC16C73A	4K x 14	192 x 8
PIC16C74	4K x 14	192 x 8
PIC16C74A	4K x 14	192 x 8
PIC16C76	8K x 14	368 x 8
PIC16C77	8K x 14	386 x 8

The PIC16CXX can directly or indirectly address its register files or data memory. All special function registers, including the program counter, are mapped in the data memory. The PIC16CXX has an orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of 'special optimal situations' make programming with the PIC16CXX simple yet efficient. In addition, the learning curve is reduced significantly.

PIC16CXX devices contain an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between the data in the working register and any register file.

The ALU is 8-bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the working register (W register). The other operand is a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. The C and DC bits operate as a borrow bit and a digit borrow out bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

## 4.2.2.1 STATUS REGISTER Applicable Devices 72|73|73A|74|74A|76|77

The STATUS register, shown in Figure 4-7, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the TO and PD bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, CLRF STATUS will clear the upper-three bits and set the Z bit. This leaves the STATUS register as 000u uluu (where u = unchanged).

It is recommended, therefore, that only BCF, BSF, SWAPF and MOVWF instructions are used to alter the STATUS register because these instructions do not affect the Z, C or DC bits from the STATUS register. For other instructions, not affecting any status bits, see the "Instruction Set Summary."

- **Note 1:** For those devices that do not use bits IRP and RP1 (STATUS<7:6>), maintain these bits clear to ensure upward compatibility with future products.
- Note 2: The C and DC bits operate as a borrow and digit borrow bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x		
IRP	RP1	RP0	TO	PD	Z	DC	С	R = Readable bit	
bit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset	
bit 7:	1 = Bank 2	ster Bank \$ 2, 3 (100h 0, 1 (00h -	- 1FFh)	used for ir	ndirect addr	essing)			
bit 6-5:	11 = Bank 10 = Bank 01 = Bank 00 = Bank	: Register E < 3 (180h - < 2 (100h - < 1 (80h - F < 0 (00h - 7 k is 128 by	1FFh) 17Fh) Fh) ′Fh)	ct bits (use	ed for direct	addressin	g)		
oit 4:	TO: Time-out bit 1 = After power-up, CLRWDT instruction, or SLEEP instruction 0 = A WDT time-out occurred								
bit 3:	•	r-down bit power-up o ecution of t	•						
bit 2:		sult of an a			peration is z				
bit 1:	<b>DC</b> : Digit carry/borrow bit (ADDWF, ADDLW, SUBLW, SUBWF instructions) (for borrow the polarity is reversed) 1 = A carry-out from the 4th low order bit of the result occurred 0 = No carry-out from the 4th low order bit of the result								
bit 0:	<ul> <li>0 = No carry-out from the 4th low order bit of the result</li> <li>C: Carry/borrow bit (ADDWF, ADDLW, SUBLW, SUBWF instructions)</li> <li>1 = A carry-out from the most significant bit of the result occurred</li> <li>0 = No carry-out from the most significant bit of the result occurred</li> <li>Note: For borrow the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (RRF, RLF) instructions, this bit is loaded with either the high or low order bit of the source register.</li> </ul>								

## FIGURE 4-7: STATUS REGISTER (ADDRESS 03h, 83h, 103h, 183h)

## FIGURE 4-13: PIR1 REGISTER PIC16C73/73A/74/74A/76/77 (ADDRESS 0Ch)

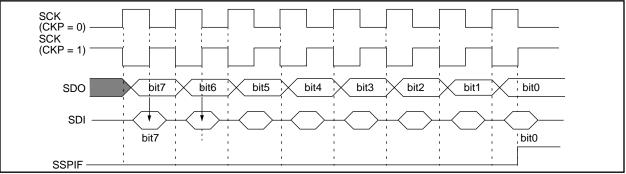
0 (1)	R/W-0 ADIF		R-0 RCIF		R-0 TXIF	R/W			R/W-0 CCP1IF		1	2/W-0 //R2IF		R/W TMR	-	D		Read	doblo	hit		
	ADI		Keir			001					<u> </u>	/1//211			bit0	W U	/ =	Writa Unim read	able b nplen   as '(	oit nenteo		
1	= A re	ad	arallel or a wr d or wri	ite o	peratic	n has							eare	ed in	soft	war	e)					
1	<ul> <li>ADIF: A/D Converter Interrupt Flag bit</li> <li>1 = An A/D conversion completed (must be cleared in software)</li> <li>0 = The A/D conversion is not complete</li> </ul>																					
1	<b>RCIF</b> : USART Receive Interrupt Flag bit 1 = The USART receive buffer is full (cleared by reading RCREG) 0 = The USART receive buffer is empty																					
1	<ul> <li>TXIF: USART Transmit Interrupt Flag bit</li> <li>1 = The USART transmit buffer is empty (cleared by writing to TXREG)</li> <li>0 = The USART transmit buffer is full</li> </ul>																					
1	<b>SSPIF</b> : Synchronous Serial Port Interrupt Flag bit 1 = The transmission/reception is complete (must be cleared in software) 0 = Waiting to transmit/receive																					
<u>C</u> 1 0 <u>C</u> 1 0 <u>P</u>	<b>CCP1IF</b> : CCP1 Interrupt Flag bit <u>Capture Mode</u> 1 = A TMR1 register capture occurred (must be cleared in software)         0 = No TMR1 register capture occurred <u>Compare Mode</u> 1 = A TMR1 register compare match occurred (must be cleared in software)         0 = No TMR1 register compare match occurred (must be cleared in software)         0 = No TMR1 register compare match occurred <u>PWM Mode</u> Unused in this mode																					
1	= TMF	R2 t	MR2 to o PR2 R2 to P	mate	ch occu	urred (	mus		-	ed	l in	softw	are	e)								
1	<b>TMR1IF</b> : TMR1 Overflow Interrupt Flag bit 1 = TMR1 register overflowed (must be cleared in software) 0 = TMR1 register did not overflow																					
			73A/76 evices,							S	lav	e Port	im	plen	nente	ed,	this	s bit l	ocat	ion is	rese	rved
o errupt pal er	on thes	e de ts ge it, G	evices, et set wh IE (INT)	alwa nen a	ays mai	intain t	his l	bit n o	clear.	ga	ardle	ess of t	he	state	of its	cor	rre	es	espondi	esponding e	esponding enable	is bit location is rese esponding enable bit or lag bits are clear prior to

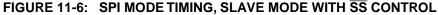
The  $\overline{SS}$  pin allows a synchronous slave mode. The SPI must be in slave mode (SSPCON<3:0> = 04h) and the TRISA<5> bit must be set the for synchronous slave mode to be enabled. When the  $\overline{SS}$  pin is low, transmission and reception are enabled and the SDO pin is driven. When the  $\overline{SS}$  pin goes high, the SDO pin is no longer driven, even if in the middle of a transmitted byte, and becomes a floating output. If the  $\overline{SS}$  pin is taken low without resetting SPI mode, the transmission will continue from the

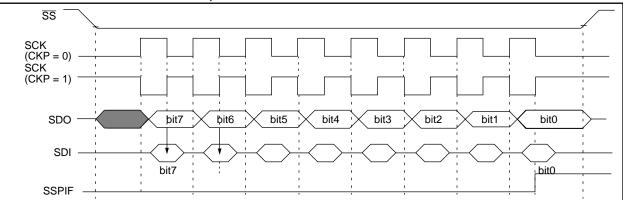
point at which it was taken high. External pull-up/ pull-down resistors may be desirable, depending on the application.

To emulate two-wire communication, the SDO pin can be connected to the SDI pin. When the SPI needs to operate as a receiver the SDO pin can be configured as an input. This disables transmissions from the SDO. The SDI can always be left as an input (SDI function) since it cannot create a bus conflict.









	<b>TABLE 11-1:</b>	<b>REGISTERS ASSOCIATED WITH SPI OPERATION</b>
--	--------------------	------------------------------------------------

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value POF BOF	٦,	all o	e on ther ets
0Bh,8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 0	200x	0000	000u
0Ch	PIR1	PSPIF <sup>(1,2)</sup>	ADIF	RCIF <sup>(2)</sup>	TXIF <sup>(2)</sup>	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0	0000	0000	0000
8Ch	PIE1	PSPIE <sup>(1,2)</sup>	ADIE	RCIE <sup>(2)</sup>	TXIE <sup>(2)</sup>	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0	0000	0000	0000
87h	TRISC	PORTC Da	ta Directio	on Registe	er					1111 1	1111	1111	1111
13h	SSPBUF	Synchronou	us Serial I	Port Rece	ive Buffer	/Transmit	Register			xxxx x	xxxx	uuuu	uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0	0000	0000	0000
85h	TRISA	_	_	PORTA I	PORTA Data Direction Register						1111	11	1111
94h	SSPSTAT	—	—	D/Ā	Р	S	R/W	UA	BF	00 C	0000	00	0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by the SSP in SPI mode.

Note 1: Bits PSPIE and PSPIF are reserved on the PIC16C73/73A, always maintain these bits clear.

2: The PIC16C72 does not have a Parallel Slave Port or USART, these bits are unimplemented, read as '0'.

#### 12.2.2 USART ASYNCHRONOUS RECEIVER

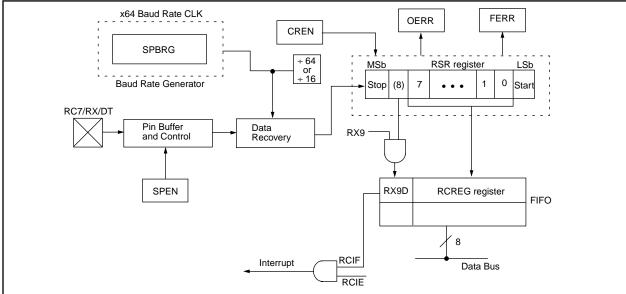
The receiver block diagram is shown in Figure 12-10. The data is received on the RC7/RX/DT pin and drives the data recovery block. The data recovery block is actually a high speed shifter operating at x16 times the baud rate, whereas the main receive serial shifter operates at the bit rate or at Fosc.

Once Asynchronous mode is selected, reception is enabled by setting bit CREN (RCSTA<4>).

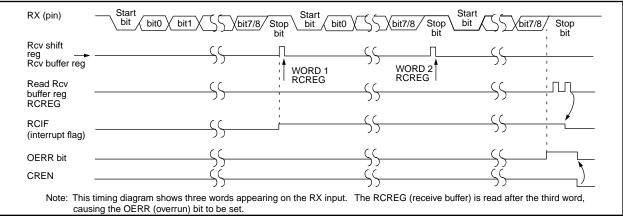
The heart of the receiver is the receive (serial) shift register (RSR). After sampling the STOP bit, the received data in the RSR is transferred to the RCREG register (if it is empty). If the transfer is complete, flag bit RCIF (PIR1<5>) is set. The actual interrupt can be enabled/ disabled by setting/clearing enable bit RCIE (PIE1<5>). Flag bit RCIF is a read only bit which is cleared by the hardware. It is cleared when the RCREG register has been read and is empty. The RCREG is a

#### FIGURE 12-10: USART RECEIVE BLOCK DIAGRAM

double buffered register, i.e. it is a two deep FIFO. It is possible for two bytes of data to be received and transferred to the RCREG FIFO and a third byte begin shifting to the RSR register. On the detection of the STOP bit of the third byte, if the RCREG register is still full then overrun error bit OERR (RCSTA<1>) will be set. The word in the RSR will be lost. The RCREG register can be read twice to retrieve the two bytes in the FIFO. Overrun bit OERR has to be cleared in software. This is done by resetting the receive logic (CREN is cleared and then set). If bit OERR is set, transfers from the RSR register to the RCREG register are inhibited, so it is essential to clear error bit OERR if it is set. Framing error bit FERR (RCSTA<2>) is set if a stop bit is detected as clear. Bit FERR and the 9th receive bit are buffered the same way as the receive data. Reading the RCREG, will load bits RX9D and FERR with new values, therefore it is essential for the user to read the RCSTA register before reading RCREG register in order not to lose the old FERR and RX9D information.









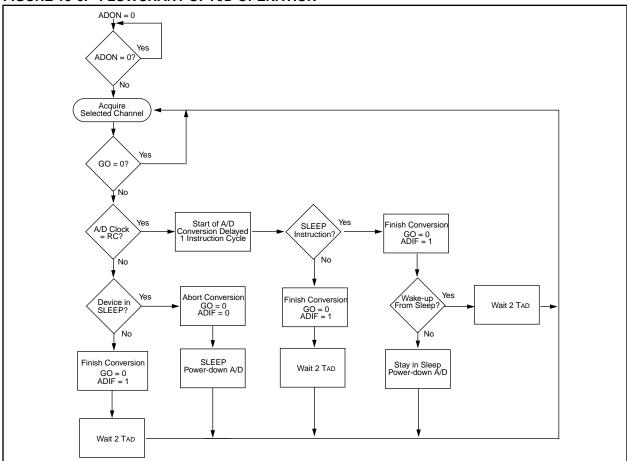


TABLE 13-2: REGISTERS/BITS ASSOCIATED WITH A/D, PIC16C72

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh,8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	-	—	SSPIF	CCP1IF	TMR2IF	TMR1IF	-0 0000	-0 0000
8Ch	PIE1	—	ADIE	-	_	SSPIE	CCP1IE	TMR2IE	TMR1IE	-0 0000	-0 0000
1Eh	ADRES	A/D Res	sult Regist	ter						xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/DONE	—	ADON	0000 00-0	0000 00-0
9Fh	ADCON1	—	—	_	_	_	PCFG2	PCFG1	PCFG0	000	000
05h	PORTA	_	_	RA5	RA4	RA3	RA2	RA1	RA0	0x 0000	0u 0000
85h	TRISA	_		PORTA	Data D	irection F	11 1111	11 1111			

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for A/D conversion.

## 14.4 Power-on Reset (POR), Power-up Timer (PWRT) and Oscillator Start-up Timer (OST), and Brown-out Reset (BOR) Applicable Devices 72 73 73 74 74 76 77

#### 14.4.1 POWER-ON RESET (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.5V - 2.1V). To take advantage of the POR, just tie the  $\overline{MCLR}$  pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified. See Electrical Specifications for details.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, ...) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met. Brown-out Reset may be used to meet the startup conditions.

For additional information, refer to Application Note AN607, "*Power-up Trouble Shooting.*"

#### 14.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only, from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

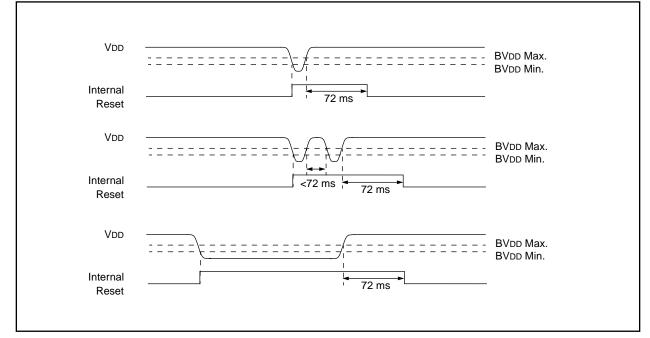
#### 14.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

# 14.4.4 BROWN-OUT RESET (BOR) Applicable Devices 72 73 73 74 74 76 77

A configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V (3.8V - 4.2V range) for greater than parameter #35, the brown-out situation will reset the chip. A reset may not occur if VDD falls below 4.0V for less than parameter #35. The chip will remain in Brown-out Reset until VDD rises above BVDD. The Power-up Timer will now be invoked and will keep the chip in RESET an additional 72 ms. If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above BVDD, the Power-up Timer will execute a 72 ms time delay. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 14-9 shows typical brown-out situations.



### FIGURE 14-9: BROWN-OUT SITUATIONS

## 14.5 <u>Interrupts</u> Applicable Devices 72|73|73|74|74|76|77

The PIC16C7X family has up to 12 sources of interrupt. The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note:	Individual interrupt flag bits are set regard-	
	less of the status of their corresponding	l
	mask bit or the GIE bit.	l

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set regardless of the status of the GIE bit. The GIE bit is cleared on reset.

The "return from interrupt" instruction, RETFIE, exits the interrupt routine as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2, and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 14-17). The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

- Note: For the PIC16C73/74, if an interrupt occurs while the Global Interrupt Enable (GIE) bit is being cleared, the GIE bit may unintentionally be re-enabled by the user's Interrupt Service Routine (the RETFIE instruction). The events that would cause this to occur are:
  - 1. An instruction clears the GIE bit while an interrupt is acknowledged.
  - 2. The program branches to the Interrupt vector and executes the Interrupt Service Routine.
  - The Interrupt Service Routine completes with the execution of the RET-FIE instruction. This causes the GIE bit to be set (enables interrupts), and the program returns to the instruction after the one which was meant to disable interrupts.

Perform the following to ensure that interrupts are globally disabled:

LOOP	BCF	INTCON,	GIE	;	Disable global
				;	interrupt bit
	BTFSC	INTCON,	GIE	;	Global interrupt
				;	disabled?
	GOTO	LOOP		;	NO, try again
	:			;	Yes, continue
				;	with program
				;	flow

#### 14.5.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered: either rising if bit INTEDG (OPTION<6>) is set, or falling, if the INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). Flag bit INTF must be cleared in software in the interrupt service routine before re-enabling this interrupt. The INT interrupt can wake-up the processor from SLEEP, if bit INTE was set prior to going into SLEEP. The status of global interrupt enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 14.8 for details on SLEEP mode.

#### 14.5.2 TMR0 INTERRUPT

An overflow (FFh  $\rightarrow$  00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>). (Section 7.0)

#### 14.5.3 PORTB INTCON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>). (Section 5.2)

Note:	For the PIC16C73/74, if a change on the						
	I/O pin should occur when the read opera-						
	tion is being executed (start of the Q2						
	cycle), then the RBIF interrupt flag may not						
	get set.						

## 14.6 <u>Context Saving During Interrupts</u> Applicable Devices

## 72 73 73A 74 74A 76 77

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt i.e., W register and STATUS register. This will have to be implemented in software.

Example 14-1 stores and restores the STATUS, W, and PCLATH registers. The register, W\_TEMP, must be defined in each bank and must be defined at the same offset from the bank base address (i.e., if W\_TEMP is defined at 0x20 in bank 0, it must also be defined at 0xA0 in bank 1).

The example:

- a) Stores the W register.
- b) Stores the STATUS register in bank 0.
- c) Stores the PCLATH register.
- d) Executes the ISR code.
- e) Restores the STATUS register (and bank select bit).
- f) Restores the W and PCLATH registers.

### EXAMPLE 14-1: SAVING STATUS, W, AND PCLATH REGISTERS IN RAM

MOVWF SWAPF CLRF	W_TEMP STATUS,W STATUS	;Copy W to TEMP register, could be bank one or zero ;Swap status to be saved into W ;bank 0, regardless of current bank, Clears IRP,RP1,RP0
MOVWF	STATUS_TEMP	;Save status to bank zero STATUS_TEMP register
MOVF	PCLATH, W	;Only required if using pages 1, 2 and/or 3
MOVWF	PCLATH_TEMP	;Save PCLATH into W
CLRF	PCLATH	;Page zero, regardless of current page
BCF	STATUS, IRP	;Return to Bank 0
MOVF	FSR, W	;Copy FSR to W
MOVWF	FSR_TEMP	;Copy FSR from W to FSR_TEMP
:		
:(ISR)		
:		
MOVF	PCLATH_TEMP, W	;Restore PCLATH
MOVWF	PCLATH	;Move W into PCLATH
SWAPF	STATUS_TEMP,W	;Swap STATUS_TEMP register into W
		;(sets bank to original state)
MOVWF	STATUS	;Move W into STATUS register
SWAPF	W_TEMP,F	;Swap W_TEMP
SWAPF	W_TEMP,W	;Swap W_TEMP into W

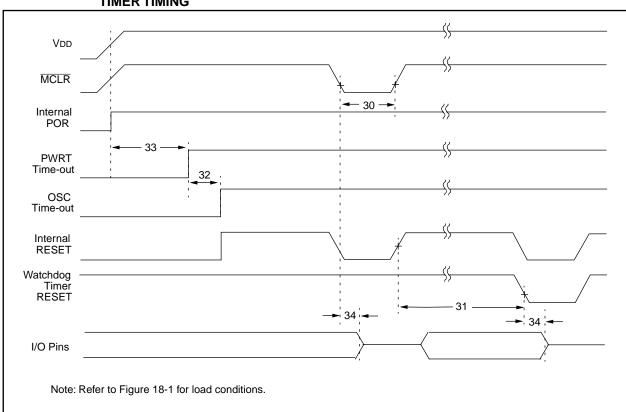
## Applicable Devices 72 73 73A 74 74A 76 77

## 18.4 <u>Timing Parameter Symbology</u>

The timing parameter symbols have been created following one of the following formats:

1. TppS2p	pS	3. Tcc:st	(I <sup>2</sup> C specifications only)
2. TppS		4. Ts	(I <sup>2</sup> C specifications only)
Т			
F	Frequency	Т	Time
Lowerca	se letters (pp) and their meanings:		
рр			
сс	CCP1	osc	OSC1
ck	CLKOUT	rd	RD
CS	CS	rw	RD or WR
di	SDI	SC	SCK
do	SDO	SS	SS
dt	Data in	tO	ТОСКІ
io	I/O port	t1	T1CKI
mc	MCLR	wr	WR
	se letters and their meanings:		
S			
F	Fall	P	Period
H	High	R	Rise
	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance
I <sup>2</sup> C only			
AA	output access	High	High
BUF	Bus free	Low	Low
Tcc:st (	I <sup>2</sup> C specifications only)		
CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	STOP condition
STA	START condition		
FIGURE 1	8-1: LOAD CONDITIONS		
	Load condition 1	Loa	d condition 2
	VDD/2		
	Pin CL Vss	Pin	
	$RL = 464\Omega$		Vss
		, but including	PORTD and PORTE outputs as
	15 pF for OSC2 output		
	Note: PORTD and PORTE are not imple	emented on th	e PIC16C73.

Applicable Devices 72 73 73A 74 74A 76 77



## FIGURE 18-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

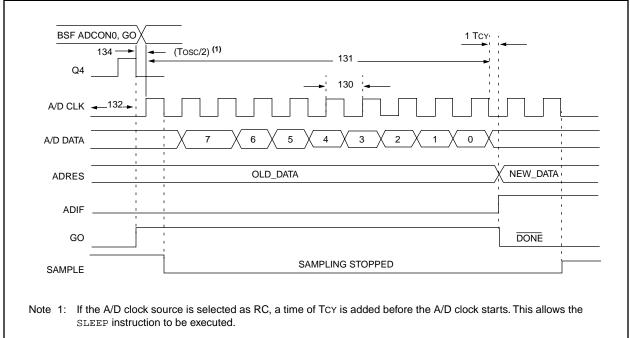
## TABLE 18-4:RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP<br/>TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	100	—	_	ns	VDD = 5V, -40°C to +85°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +85°C
32	Tost	Oscillation Start-up Timer Period	_	1024Tosc	—	_	Tosc = OSC1 period
33*	Tpwrt	Power up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +85°C
34	Tıoz	I/O Hi-impedance from MCLR Low or Watchdog Timer Reset	—	_	100	ns	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested. 
 Applicable Devices
 72
 73
 73A
 74
 74A
 76
 77

## FIGURE 19-14: A/D CONVERSION TIMING



## TABLE 19-14: A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Тур†	Мах	Units	Conditions
130	TAD	A/D clock period	PIC16 <b>C</b> 73A/74A	1.6	_	_	μs	Tosc based, VREF ≥ 3.0V
			PIC16 <b>LC</b> 73A/74A	2.0	—	_	μs	Tosc based, VREF full range
			PIC16 <b>C</b> 73A/74A	2.0	4.0	6.0	μs	A/D RC Mode
			PIC16 <b>LC</b> 73A/74A	3.0	6.0	9.0	μs	A/D RC Mode
131	TCNV	Conversion time (no (Note 1)	ot including S/H time)	_	9.5		TAD	
132	TACQ	Acquisition time		Note 2	20	_	μs	
				5*	_	_	μs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 20.0 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).
134	TGO	Q4 to A/D clock sta	rt	_	Tosc/2 §	_	_	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.
135	Tswc	Switching from con-	vert $\rightarrow$ sample time	1.5 §	_	_	TAD	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

Note 1: ADRES register may be read on the following TCY cycle.

2: See Section 13.1 for min conditions.

\*

## Applicable Devices 72 73 73A 74 74A 76 77

## 20.1 DC Characteristics: PIC16C76/77-04 (Commercial, Industrial, Extended) PIC16C76/77-10 (Commercial, Industrial, Extended) PIC16C76/77-20 (Commercial, Industrial, Extended)

			Standa	ard Op	eratin	g Cond	litions (unless otherwise stated)
	ARACTERISTICS		Operati				$0^{\circ}C \leq TA \leq +125^{\circ}C$ for extended,
	ARACTERISTICS		-	-		-4	$0^{\circ}C \leq TA \leq +85^{\circ}C$ for industrial and
						0°	C $\leq$ TA $\leq$ +70°C for commercial
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001 D001A	Supply Voltage	Vdd	4.0 4.5		6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	Svdd	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	Bvdd	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
			3.7	4.0	4.4	V	Extended Range Only
D010	Supply Current (Note 2,5)	IDD	-	2.7	5	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	mA	HS osc configuration Fosc = 20 MHz, VDD = 5.5V
D015*	Brown-out Reset Current (Note 6)	$\Delta$ IBOR	-	350	425	μA	BOR enabled VDD = 5.0V
D020	Power-down Current	IPD	-	10.5	42	μA	VDD = $4.0V$ , WDT enabled, $-40^{\circ}C$ to $+85^{\circ}C$
D021	(Note 3,5)		-	1.5	16	μA	VDD = 4.0V, WDT disabled, $-0^{\circ}C$ to $+70^{\circ}C$
D021A			-	1.5	19	μΑ	VDD = $4.0V$ , WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$
D021B			-	2.5	19	μA	VDD = $4.0V$ , WDT disabled, $-40^{\circ}C$ to $+125^{\circ}C$
D023*	Brown-out Reset Current (Note 6)	$\Delta$ IBOR	-	350	425	μΑ	BOR enabled VDD = 5.0V

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

 $\overline{MCLR}$  = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.

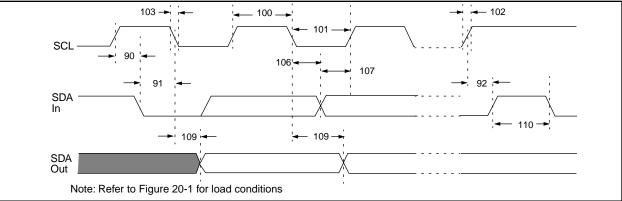
4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

## Applicable Devices 72 73 73A 74 74A 76 77

## FIGURE 20-14: I<sup>2</sup>C BUS DATA TIMING



## TABLE 20-10: I<sup>2</sup>C BUS DATA REQUIREMENTS

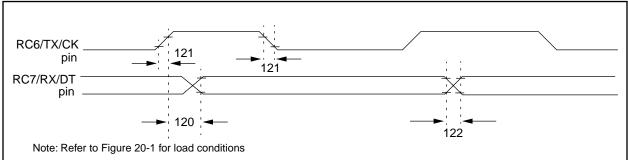
Parameter No.	Sym	Characteristic		Min	Мах	Units	Conditions
100	Thigh	Clock high time	100 kHz mode	4.0	_	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	0.6	_	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5Tcy	—		
101	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	1.3	_	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5Tcy	_		
102	Tr	SDA and SCL rise	100 kHz mode	-	1000	ns	
		time	400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
103	Tf	SDA and SCL fall time	100 kHz mode	-	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
90	TSU:STA	START condition	100 kHz mode	4.7	—	μs	Only relevant for repeated
		setup time	400 kHz mode	0.6	—	μs	START condition
91	THD:STA	START condition hold	100 kHz mode	4.0	—	μs	After this period the first clock
		time	400 kHz mode	0.6	—	μs	pulse is generated
106	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92	TSU:STO	STOP condition setup	100 kHz mode	4.7	—	μs	
		time	400 kHz mode	0.6	—	μs	
109	ΤΑΑ	Output valid from	100 kHz mode	_	3500	ns	Note 1
		clock	400 kHz mode	_	—	ns	
110	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free
			400 kHz mode	1.3	—	μs	before a new transmission can start
	Cb	Bus capacitive loading			400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

2: A fast-mode (400 kHz) I<sup>2</sup>C-bus device can be used in a standard-mode (100 kHz) I<sup>2</sup>C-bus system, but the requirement tsu;DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I<sup>2</sup>C bus specification) before the SCL line is released.

Applicable Devices 72 73 73A 74 74A 76 77

## FIGURE 20-15: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

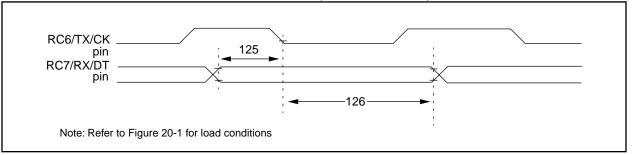


## TABLE 20-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	PIC16 <b>C</b> 76/77 PIC16 <b>LC</b> 76/77	_	_	80 100	ns ns	
121	Tckrf	Clock out rise time and fall time	PIC16 <b>C</b> 76/77			45	ns	
		(Master Mode)	PIC16 <b>LC</b> 76/77	—		50	ns	
122	Tdtrf	Data out rise time and fall time	PIC16 <b>C</b> 76/77	—	-	45	ns	
			PIC16 <b>LC</b> 76/77	—	—	50	ns	

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

#### FIGURE 20-16: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



### TABLE 20-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
125	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before $CK \downarrow (DT setup time)$	15	_	_	ns	
126	TckL2dtl	Data hold after CK $\downarrow$ (DT hold time)	15	—	—	ns	

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

# PIC16C7X

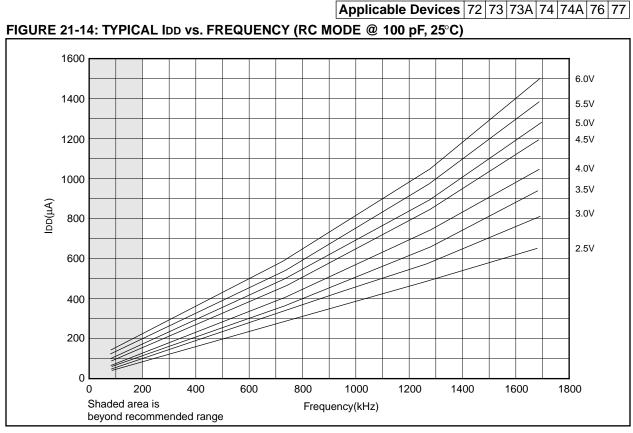
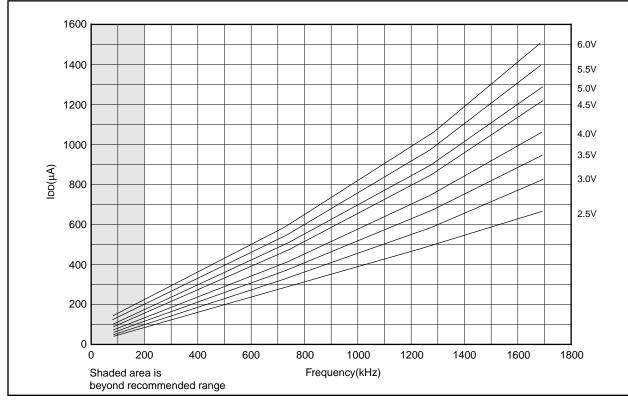


FIGURE 21-15: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 100 pF, -40°C TO 85°C)



Data based on matrix samples. See first page of this section for details.

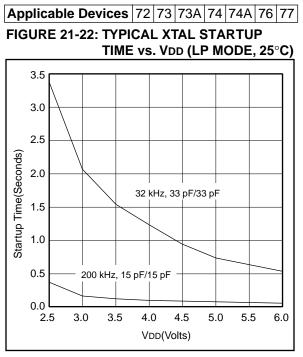
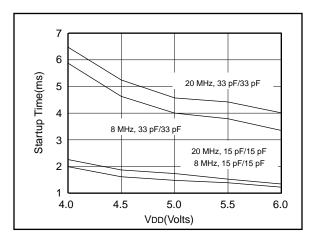


FIGURE 21-23: TYPICAL XTAL STARTUP TIME vs. Vdd (HS MODE, 25°C)



## FIGURE 21-24: TYPICAL XTAL STARTUP TIME vs. VDD (XT MODE, 25°C)

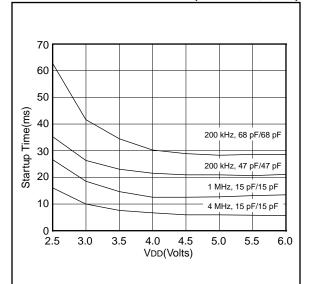


TABLE 21-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATORS

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
	4		
Crystals Used			
32 kHz	Epson C-00	)1R32.768K-A	± 20 PPM
200 kHz	STD XTL 2	00.000KHz	± 20 PPM
1 MHz	ECS ECS-1	10-13-1	± 50 PPM
4 MHz	ECS ECS-4	10-20-1	± 50 PPM
8 MHz	EPSON CA	-301 8.000M-C	± 30 PPM
20 MHz	EPSON CA	-301 20.000M-C	± 30 PPM

## E.3 PIC16C15X Family of Devices

		PIC16C154	PIC16CR154	PIC16C156	PIC16CR156	PIC16C158	PIC16CR158
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20
	EPROM Program Memory (x12 words)	512		1K		2К	
Memory	ROM Program Memory (x12 words)	-	512	—	1K	—	2К
	RAM Data Memory (bytes)	25	25	25	25	73	73
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0	TMR0
	I/O Pins	12	12	12	12	12	12
	Voltage Range (Volts)	3.0-5.5	2.5-5.5	3.0-5.5	2.5-5.5	3.0-5.5	2.5-5.5
Features	Number of Instructions	33	33	33	33	33	33
	Packages	18-pin DIP, SOIC; 20-pin SSOP					

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.

## E.4 PIC16C5X Family of Devices

		PIC16C52	PIC16C54	PIC16C54A	PIC16CR54A	PIC16C55	PIC16C56
Clock	Maximum Frequency of Operation (MHz)	4	20	20	20	20	20
	EPROM Program Memory (x12 words)	384	512	512	—	512	1K
Memory	ROM Program Memory (x12 words)	-	—	—	512	—	—
	RAM Data Memory (bytes)	25	25	25	25	24	25
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0	TMR0
	I/O Pins	12	12	12	12	20	12
	Voltage Range (Volts)	2.5-6.25	2.5-6.25	2.0-6.25	2.0-6.25	2.5-6.25	2.5-6.25
Features	Number of Instructions	33	33	33	33	33	33
	Packages	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin DIP, SOIC, SSOP	18-pin DIP, SOIC; 20-pin SSOP

		PIC16C57	PIC16CR57B	PIC16C58A	PIC16CR58A
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20
	EPROM Program Memory (x12 words)	2K	-	2К	—
Memory	ROM Program Memory (x12 words)	-	2К	—	2K
	RAM Data Memory (bytes)	72	72	73	73
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0
	I/O Pins	20	20	12	12
	Voltage Range (Volts)	2.5-6.25	2.5-6.25	2.0-6.25	2.5-6.25
Features	Number of Instructions	33	33	33	33
	Packages	28-pin DIP, SOIC, SSOP	28-pin DIP, SOIC, SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer (except PIC16C52), selectable code protect and high I/O current capability.

# PIC16C7X

Registers
FSR 20
Summary29 INDF
Summary
INTCON
Summary29 Maps
PIC16C7221
PIC16C73
PIC16C73A
PIC16C74
PIC16C76
PIC16C77
OPTION
Summary
PCL Summary29
PCLATH
Summary
PORTB
Summary
Reset Conditions136 SSPBUF
SCROF Section
SSPCON
Diagram79
SSPSR
Section
SSPSTAT
Section
STATUS
Summary29
Summary
TMR0 Summary29
TRISB
Summary
Reset 129, 133
Reset Conditions for Special Registers
RP0 bit20, 30 RP1 bit
RP1 bit
RX9D bit
S
S
SCK
SCL
SDI
SDO
Serial Communication Interface (SCI) Module, See USART Services
One-Time-Programmable (OTP)7
Quick-Turnaround-Production (QTP)7
Serialized Quick-Turnaround Production (SQTP)7
Slave Mode
SCL
SLEEP
SMP
Software Simulator (MPSIM) 165
SPBRG

SPBRG Register	26 28
Special Event Trigger	
Special Features of the CPU	129
Special Function Registers	
PIC16C72	23
PIC16C73	25, 27
PIC16C73A	25 27
PIC16C74	
PIC16C74A	,
PIC16C76	
PIC16C77	
Special Function Registers, Section	23
SPEN bit	
SPI	
Block Diagram	00.05
-	
Master Mode	
Master Mode Timing	87
Mode	80
Serial Clock	
Serial Data In	
Serial Data Out	
Slave Mode Timing	
Slave Mode Timing Diagram	87
Slave Select	85
SPI clock	86
SPI Mode	85
SSPCON	
SSPSTAT	
SPI Clock Edge Select bit, CKE	83
SPI Data Input Sample Phase Select bit, SMP	83
SPI Mode	80
SREN bit	
SS	
66D	
SSP	
Module Overview	77
	77
Module Overview	77
Module Overview Section SSPBUF	77 77 86
Module Overview Section SSPBUF SSPCON	77 77 86 84
Module Overview Section SSPBUF SSPCON SSPSR	77 
Module Overview Section SSPBUF SSPCON SSPSR SSPSTAT	77 
Module Overview Section SSPBUF SSPCON SSPSR SSPSTAT SSP in I <sup>2</sup> C Mode - See I <sup>2</sup> C	
Module Overview Section SSPBUF SSPCON SSPSR SSPSTAT SSP in I <sup>2</sup> C Mode - See I <sup>2</sup> C SSPADD	
Module Overview Section SSPBUF SSPCON SSPSR SSPSTAT SSP in I <sup>2</sup> C Mode - See I <sup>2</sup> C	
Module Overview Section SSPBUF SSPCON SSPSR SSPSTAT SSP in I <sup>2</sup> C Mode - See I <sup>2</sup> C SSPADD	
Module Overview Section SSPBUF SSPCON SSPSR SSPSTAT SSP in I <sup>2</sup> C Mode - See I <sup>2</sup> C SSPADD SSPADD Register	
Module Overview Section SSPBUF SSPCON SSPSR SSPSTAT SSP in I <sup>2</sup> C Mode - See I <sup>2</sup> C SSPADD SSPADD Register	
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Module Overview Section SSPBUF SSPCON SSPSR SSPSTAT SSP in I <sup>2</sup> C Mode - See I <sup>2</sup> C SSPADD SSPADD Register	
Module Overview Section	
Module Overview	
Module Overview	
Module Overview Section SSPBUF SSPCON SSPSR SSPSTAT SSP in 1 <sup>2</sup> C Mode - See 1 <sup>2</sup> C SSPADD SSPADD Register SSPADD Register SSPBUF Register SSPEN SSPCON Register SSPEN SSPEN SSPIE bit SSPIE bit SSPIF bit SSPIF bit SSPM3:SSPM0 SSPOV SSPSTAT SSPSTAT	
Module Overview	